Product Change Notification: CAAN-12OSGH090

Date:

16-Jun-2026

Product Category:

32-Bit Microprocessors

Notification Subject:

CCB 7410 Final Notice: Qualification of ASEM as an additional assembly site for AT91SAM9260B-CU and AT91SAM9260B-CU-999 catalog part numbers (CPN) available in 217L LFBGA (15x15x1.4mm) package.

Affected CPNs:

CAAN-12OSGH090_Affected_CPN_06162026.pdf
CAAN-12OSGH090_Affected_CPN_06162026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ASEM as an additional assembly site for AT91SAM9260B-CU and AT91SAM9260B-CU-999 catalog part numbers (CPN) available in 217L LFBGA (15x15x1.4mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**		**Change** (Yes/No)
Assembly Site	ATX Semiconductor (Shanghai) Co.	ATX Semiconductor (Shanghai) Co.	ASE Group - Malaysia (ASEM)	Yes

	Ltd (ASSH)	Ltd (ASSH)		
Wire Material	Au	Au	Au	No
Die Attach Material	2100AS	2100AS	ABL2100A	Yes
Molding Compound Material	KE-G1250	KE-G1250	KEG 1250LKDS-C	Yes
Core Material	CCL-HL832NX	CCL-HL832NX	CCL-HL832NX	No
Substrate Material	AUS308	AUS308	AUS308	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ASEM as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 10 July 2026 (date code: 2628)

Note Below EFSD: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	February 2025					**>**	**June 2026**					**July 2026**			
Work Week	05	06	07	08	09		23	24	25	26	27	28	29	30	31
Initial PCN Issue Date				X											
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date												X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 18, 2025: Issued initial notification
June 16, 2026: Issued final notification. Attached the qualification report. Added column "Change (Yes/No)" in the pre and post change table. Provided estimated first ship date to be on July 10, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN CAAN-12OSGH090 Qual Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

AT91SAM9260B-CU

AT91SAM9260B-CU-999

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: CAAN-12OSGH090

Date:
June 08, 2026

Qualification of ASEM as an additional assembly site for AT91SAM9260B-CU and AT91SAM9260B-CU-999 catalog part numbers (CPN) available in 217L LFBGA (15x15x1.4mm) package.

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Package Qualification Report

Purpose: Qualification of ASEM as an additional assembly site for AT91SAM9260B-CU and AT91SAM9260B-CU-999 catalog part numbers (CPN) available in 217L LFBGA (15x15x1.4mm) package.

CCB No.: 7410

Misc.	**Assembly site**	ASEM
	BD Number	BD-002991 rev 02
	MP Code (MPC)	58A937ATBC02
	Part Number (CPN)	AT91SAM9260B-CU
	MSL information	MSL3/260
	Assembly Shipping Media (T/R, Tube/Tray)	TRAY
	Base Quantity Multiple (BQM)	126
Substrate	**Core Material**	CCL-HL832NX
	Core Thickness	250+/-30 UM
	L1/L2 Thickness	18 UM MIN
	SM Material	Aus308
	Process	STD
	SM Thickness	30+/-10 UM
	Part Number	14ABS7012456XLM
	Drill Size	150+/-25 UM
	Line/Space Specs	30/30 UM MIN
Bond Wire	**Material**	Au
Die Attach	**Part Number**	ABL2100A
	Conductive	Yes
MC	**Part Number**	KEG 1250LKDS-C
PKG	**PKG Type**	LFBGA
	Pin/Ball Count	217
	PKG width/size	15x15x1.4 mm
	Solder Ball Material	SAC105

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Package Qualification Report

Manufacturing Information:

Assembly Lot No.
ASEM255200019.000
ASEM255200020.000
ASEM255200021.000

Result: [X] Pass [ ] Fail [ ] _____

Qualification of 58A93 AT91SAM9260B-CU Au 0.9mil wire in 217L LFBGA 15x15x1.4mm (ATB) at ASEM is qualified for MSL 3 at 260°C as per JESD22A113 and is Passed in accordance to QCI-39000.

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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113; IPC/JEDEC J-STD-020		
Test Condition	**MSL 3:** 150C 24-hour Bake. 192-hour moisture soak at 30ºC/60RH. 3x Reflow at 260ºC max.		
Required Sample Size	231 each lot / 3 lots		
Electrical Test at +85ºC (Fail / Pass)	0/300	0/300	0/300
Result	Pass		

High Temp Storage

Test Method	JESD22-A103
Test Condition	150°C / **504** hours
Required Sample Size	45 units / 1 Lot
Electrical Test at +85ºC (Fail / Pass)	0/60
Result	Pass

Test Condition	150°C / **1008** hours
Required Sample Size	45 units / 1 Lot
Electrical Test at +85ºC (Fail / Pass)	0/60
Result	Pass

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55ºC / 125ºC Air to Air / **1000** Cycles		
Required Sample Size	77 each lot / 3 lots		
Electrical Test at +85ºC (Fail / Pass)	0/90	0/90	0/90
WBP/WBS (Fail/Pass)	Pass	Pass	Pass
Overall Result	Pass		

Unbiased HAST

Test Method	JESD22-A18		
Test Condition	+110ºC / 85% RH / **264** hours		
Required Sample Size	77 each lot / 3 lots		
Electrical Test at +85ºC (Fail / Pass)	0/85	0/85	0/85
Result	Pass		

Test Condition	+110ºC / 85% RH / **528** hours		
Required Sample Size	77 each lot / 3 lots		
Electrical Test at +85ºC (Fail / Pass)	0/85	0/85	0/85
Result	Pass		

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Package Qualification Report

Physical Dimension (0Hr)

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units / 3 lots
Result (Pass/Fail)	Pass

Mechanical Data (0Hr)

Wire Bond Pull (WBP)

Test Method	Mil. Std. 883-2011
Required Sample Size	30 bonds from a min. 5 devices.
Result (Pass/Fail)	Pass

Wire Ball Shear (WBS)

Test Method	CDF-AEC-Q100-001
Required Sample Size	30 bonds from a min. 5 devices.
Result (Pass/Fail)	Pass

Solder Ball Shear (SBS)

Test Method	JESD22B117A
Required Sample Size	30 bonds from a min. 5 devices.
Result (Pass/Fail)	Pass